

Global and United States Wire Bonder Equipment Market Research by Company, Type & Application 2013-2025

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Abstracts

SUMMARY

Wire bonder equipment is the machinery used for making interconnects between an IC or any other semiconductor device at the time of packaging. This interconnection ensures the flow of electricity in the semiconductor device. The thin-wire used to make these connections are usually made of copper, gold, aluminum, or silver. Wire bonder equipment is part of the semiconductor assembly and packaging process.

Market Segment as follows:

By Type

Ball bonders

Stud-bump bonders

Wedge bonders

By Application

Integrated Device Manufacturers (IDMs)

Outsourced Semiconductor Assembly and Test (OSAT)

By Company

ASM Pacific Technology

Kulicke& Soffa

Palomar Technologies

Besi

DIAS Automation

F&K Delvotec Bondtechnik

Hesse

Hybond

SHINKAWA Electric

Toray Engineering

West Bond

The main contents of the report including:

Section 1:

Product definition, type and application, global and United States market overview;

Section 2:

Global and United States Market competition by company;

Section 3:

Global and United States sales revenue, volume and price by type;

Section 4:

Global and United States sales revenue, volume and price by application;

Section 5:

United States export and import;

Section 6:

Company information, business overview, sales data and product specifications;

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Industry chain and raw materials;

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